## Octal D Flip-Flop with Clear

The SN74LS273 is a high-speed 8-Bit Register. The register consists of eight D-Type Flip-Flops with a Common Clock and an asynchronous active LOW Master Reset. This device is supplied in a 20-pin package featuring 0.3 inch lead spacing.

- 8-Bit High Speed Register
- Parallel Register
- Common Clock and Master Reset
- Input Clamp Diodes Limit High-Speed Termination Effects

#### **GUARANTEED OPERATING RANGES**

Symbol	Parameter	Min	Тур	Max	Unit
V <sub>CC</sub>	Supply Voltage	4.75	5.0	5.25	V
T <sub>A</sub>	Operating Ambient Temperature Range	0	25	70	°C
I <sub>OH</sub>	Output Current – High			-0.4	mA
I <sub>OL</sub>	Output Current – Low			8.0	mA

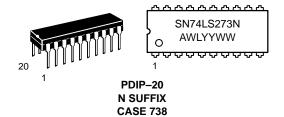


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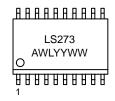
http://onsemi.com

# LOW POWER SCHOTTKY

#### MARKING DIAGRAMS







SOIC-20 DW SUFFIX CASE 751D

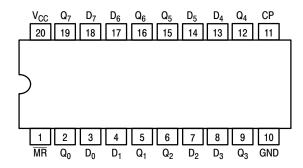
A = Assembly Location

WL = Wafer Lot YY = Year WW = Work Week

#### **ORDERING INFORMATION**

Device	Package	Shipping
SN74LS273N	PDIP-20	1440 Units/Box
SN74LS273DW	SOIC-20	2500/Tape & Reel

#### CONNECTION DIAGRAM DIP (TOP VIEW)



#### **PIN NAMES**

HIGH LOW CP Clock (Active HIGH Going Edge) Input 0.5 U.L. 0.25 U.L.  $D_0 - D_7$ Data Inputs 0.5 U.L. 0.25 U.L. ΜŘ Master Reset (Active LOW) Input 0.5 U.L. 0.25 U.L.  $Q_0 - Q_7$ Register Outputs 10 U.L. 5 U.L.

**LOADING** (Note a)

#### NOTES:

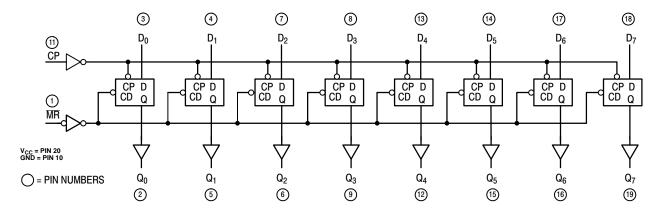
a) 1 TTL Unit Load (U.L.) = 40  $\mu$ A HIGH/1.6 mA LOW.

#### **TRUTH TABLE**

MR	СР	D <sub>x</sub>	$Q_{x}$
Г	Χ	Χ	Г
Н	$\neg$	Н	Н
Н		L	L

H = HIGH Logic Level L = LOW Logic Level X = Immaterial

#### **LOGIC DIAGRAM**



#### **FUNCTIONAL DESCRIPTION**

The SN74LS273 is an 8-Bit Parallel Register with a common Clock and common Master Reset.

When the  $\overline{MR}$  input is LOW, the Q outputs are LOW, independent of the other inputs. Information meeting the

setup and hold time requirements of the D inputs is transferred to the Q outputs on the LOW-to-HIGH transition of the clock input.

#### DC CHARACTERISTICS OVER OPERATING TEMPERATURE RANGE (unless otherwise specified)

			Limits				
Symbol	Parameter	Min	Тур	Max	Unit	Tes	t Conditions
V <sub>IH</sub>	Input HIGH Voltage	2.0			V	Guaranteed Input HIGH Voltage for All Inputs	
V <sub>IL</sub>	Input LOW Voltage			0.8	V	Guaranteed Input LOW Voltage for All Inputs	
V <sub>IK</sub>	Input Clamp Diode Voltage		-0.65	-1.5	V	V <sub>CC</sub> = MIN, I <sub>IN</sub> =	–18 mA
V <sub>OH</sub>	Output HIGH Voltage	2.7	3.5		V	V <sub>CC</sub> = MIN, I <sub>OH</sub> = or V <sub>IL</sub> per Truth T	
V	Output LOW/Vallages		0.25	0.4	V	I <sub>OL</sub> = 4.0 mA	$V_{CC} = V_{CC} MIN,$
V <sub>OL</sub>	Output LOW Voltage		0.35	0.5	V	I <sub>OL</sub> = 8.0 mA	V <sub>IN</sub> = V <sub>IL</sub> or V <sub>IH</sub> per Truth Table
	Innut I II CI I Cumant			20	μΑ	V <sub>CC</sub> = MAX, V <sub>IN</sub> =	= 2.7 V
l <sub>IH</sub>	Input HIGH Current			0.1	mA	V <sub>CC</sub> = MAX, V <sub>IN</sub> :	= 7.0 V
I <sub>IL</sub>	Input LOW Current			-0.4	mA	$V_{CC} = MAX, V_{IN} = 0.4 V$	
I <sub>OS</sub>	Short Circuit Current (Note 1.)	-20		-100	mA	V <sub>CC</sub> = MAX	
I <sub>CC</sub>	Power Supply Current			27	mA	V <sub>CC</sub> = MAX	

<sup>1.</sup> Not more than one output should be shorted at a time, nor for more than 1 second.

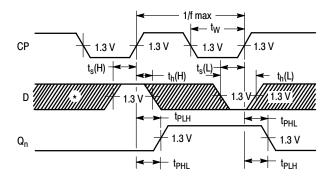
#### AC CHARACTERISTICS ( $T_A = 25$ °C, $V_{CC} = 5.0 \text{ V}$ )

		Limits				
Symbol	Parameter	Min	Тур	Max	Unit	Test Conditions
f <sub>MAX</sub>	Maximum Input Clock Frequency	30	40		MHz	Figure 1
t <sub>PHL</sub>	Propagation Delay, MR to Q Output		18	27	ns	Figure 2
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation Delay, Clock to Output		17 18	27 27	ns	Figure 1

#### AC SETUP REQUIREMENTS ( $T_A = 25$ °C, $V_{CC} = 5.0 \text{ V}$ )

		Limits				
Symbol	Parameter	Min	Тур	Max	Unit	Test Conditions
t <sub>w</sub>	Pulse Width, Clock or Clear	20			ns	Figure 1
t <sub>s</sub>	Data Setup Time	20			ns	Figure 1
t <sub>h</sub>	Hold Time	5.0			ns	Figure 1
t <sub>rec</sub>	Recovery Time	25			ns	Figure 2

#### **AC WAVEFORMS**



<sup>\*</sup>The shaded areas indicate when the input is permitted to change for predictable output performance.

Figure 1. Clock to Output Delays, Clock Pulse Width, Frequency, Setup and Hold Times Data to Clock

#### **DEFINITION OF TERMS**

SETUP TIME  $(t_s)$  — is defined as the minimum time required for the correct logic level to be present at the logic input prior to the clock transition from LOW-to-HIGH in order to be recognized and transferred to the outputs.

HOLD TIME  $(t_h)$  — is defined as the minimum time following the clock transition from LOW-to-HIGH that the logic level must be maintained at the input in order to ensure

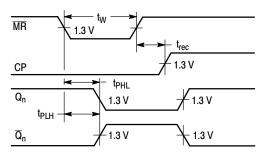


Figure 2. Master Reset to Output Delay, Master Reset Pulse Width, and Master Reset Recovery Time

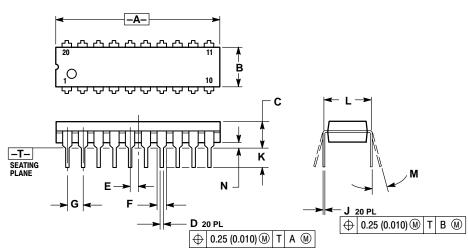
continued recognition. A negative HOLD TIME indicates that the correct logic level may be released prior to the clock transition from LOW-to-HIGH and still be recognized.

RECOVERY TIME  $(t_{rec})$  — is defined as the minimum time required between the end of the reset pulse and the clock transition from LOW-to-HIGH in order to recognize and transfer HIGH data to the Q outputs.

#### **PACKAGE DIMENSIONS**

#### **N SUFFIX**

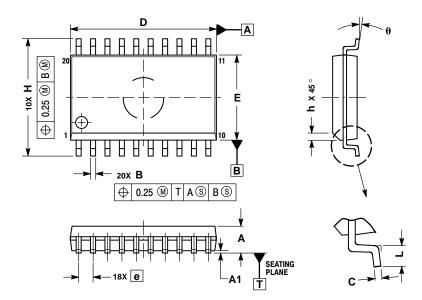
PLASTIC PACKAGE CASE 738-03 ISSUE E



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
  4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

	INC	HES	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	1.010	1.070	25.66	27.17	
В	0.240	0.260	6.10	6.60	
С	0.150	0.180	3.81	4.57	
D	0.015	0.022	0.39	0.55	
E	0.050	BSC	1.27 BSC		
F	0.050	0.070	1.27	1.77	
G	0.100	BSC	2.54 BSC		
J	0.008	0.015	0.21	0.38	
K	0.110	0.140	2.80	3.55	
L	0.300	BSC	7.62	BSC	
M	0 °	15°	0°	15°	
N	0.020	0.040	0.51	1.01	

#### **D SUFFIX** PLASTIC SOIC PACKAGE CASE 751D-05 ISSUE F



- NOTES:
  1. DIMENSIONS ARE IN MILLIMETERS.
  2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
  3. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
  4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
  5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS						
DIM	MIN	MAX					
Α	2.35	2.65					
A1	0.10	0.25					
В	0.35	0.49					
С	0.23	0.32					
D	12.65	12.95					
E	7.40	7.60					
е	1.27	BSC					
Н	10.05	10.55					
h	0.25	0.75					
L	0.50	0.90					
A	0 °	7 °					

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